

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHUI-JUNG CHIU	10/23/2012
JEN-CHIEH LO	10/23/2012
YING-CHOU CHENG	10/23/2012
RU-GUN LIU	10/23/2012
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	8, LI-HSIN RD. 6
Internal Address:	HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15811272
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	P20120590/24061.2233US03
NAME OF SUBMITTER:	ASHLEIGH STEVENS
SIGNATURE:	/Ashleigh Stevens/
DATE SIGNED:	11/14/2017
Total Attachments: 3	

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Docket No.: 2012-0590 / 24061.2233
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- (1) Chui-Jung Chiu of 14F, No. 46, Chia Cheng 2nd Street
Zhubei City, Hsinchu County 302, Taiwan, R.O.C.
- (2) Jen-Chieh Lo of 1F, No. 12, Lane 62, Chelutou Street, Sanchong District
New Taipei City 241, Taiwan, R.O.C.
- (3) Ying-Chou Cheng of 7F-2, No. 21, Sec. 1, Jiafeng 11th Road
Zhubei City, Hsinchu County 302, Taiwan, R.O.C.
- (4) Ru-Gun Liu of No. 90, Chenggong 5th Street
Zhubei City, Hsinchu County 302, Taiwan, R.O.C.

have invented certain improvements in

METHOD FOR VALIDATING MEASUREMENT DATA

for which we have filed and executed an application for Letters Patent of the United States of America on November 1, 2012 Serial No. 13/666,140; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue

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applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chui-Jung Chiu

Residence Address: 14F, No. 46, Chia Cheng 2nd Street
Zhubei City, Hsinchu County 302, Taiwan, R.O.C.

Dated: 10/23 / 2012

Chui-Jung Chiu
Inventor Signature

Inventor Name: Jen-Chieh Lo

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Dated: 10/23 / 2012

Jen-Chieh Lo
Inventor Signature

Inventor Name: Ying-Chou Cheng

Residence Address: 7F-2, No. 21, Sec. 1, Jiafeng 11th Road
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Dated: 10/23 / 2012

Ying-Chou Cheng
Inventor Signature

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Inventor Name: Ru-Gun Liu

Residence Address: No. 90, Chenggong 5th Street
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Dated: 10/23 2012

Ru-Gun Liu
Inventor Signature
